

## **Memory in silicon**

notes on work in the semiconductor industry

Michael Langenbuch Infineon Technologies AG, München

WL

BL

DRAM

1 transistor / 1 capacitor cell

#### <u>Outline:</u>

- X DRAM principle
- X Memory as product
- X Integrated circuits and semiconductor physics









## DRAM principle



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Quelle: DRAM Seminar, Infineon



## **Computer Memory**

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L: Blockschaltbild

The information is stored in the memory array. The sense amplifier (SA) reads the information and logic circuits organize the addressing and timing.

Quelle: K.Hoffmann, Systemintegration, [1]



## Feature size



The challenge for the product is the huge number of devices and the tiny size of the capacitor which stores the information.

Quelle: K.Hoffmann, Systemintegration, [1]



# Wafer, Package and Module

To deliver a reliable memory you have to test at each production step the functionality of all storage cells.





Wafer level: bit and word line repair

Package level: speed sort

## Module level:

application test





## Design, Layout and Hardware

To develop a memory product you have to bring the circuit design onto the wafer:



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# Simulation: Circuit simulation

![](_page_6_Figure_1.jpeg)

*x* The circuit is simulated recording the voltages and currents at nodes*x* From the layout parasitic elements are extracted.

**x** Also the logic is verified.

# **BUT**: For circuit simulation you have to know how your transistors are working.

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![](_page_7_Picture_0.jpeg)

## Device simulation

![](_page_7_Figure_2.jpeg)

**x** The device simulation takes care of the current and voltages on the transistor terminals.

**x** From measurements on devices with different geometries physical effects are modeled.

![](_page_8_Picture_0.jpeg)

X Simple DRAM principle.

X Challenge is the realization of reliable memory.

Interaction between electrical engineering and semiconductor physics.

### Literature

[1] K.Hoffmann: Systemintegration, Oldenburg Verlag, München (2003).

[2] D.Widmann, H.Mader, H.Friedrich:Technologie hochintegrierter Schaltungen, Springer Verlag, Berlin (1996).

![](_page_9_Picture_0.jpeg)

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Quelle: K.Hoffmann, Systemintegration, [1]